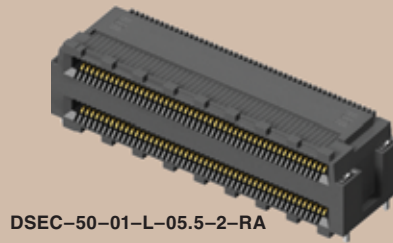
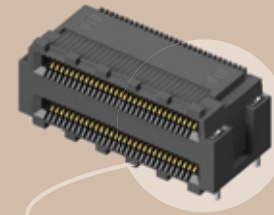


(0,80mm) .0315"

DSEC SERIES



DSEC-50-01-L-05.5-2-RA



DUAL STACK EDGE CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?DSEC

Insulator Material:

Black Liquid Crystal Polymer

Contact:

Copper Alloy

Plating:

Au or Sn over 50µ" (1,27µm) Ni

Current Rating:

Testing Now!

Operating Temp:

-55°C to +125°C

Card Insertion Depth:

(5,94mm) .234" nominal

RoHS Compliant:

Yes

Processing:

Max Processing Temp:

230°C for 60 seconds, or

260°C for 20 seconds 3x

Lead-Free Solderable:

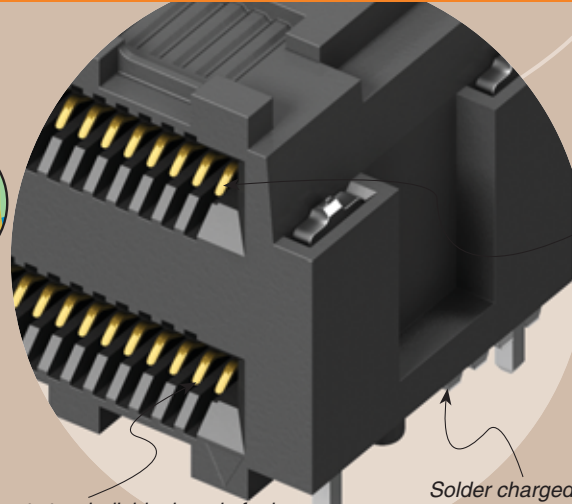
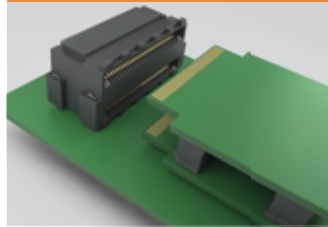
Yes

Mates with:

1,60mm (.062") thick cards



APPLICATION



Rugged Edge Rate™ contacts designed for Signal Integrity

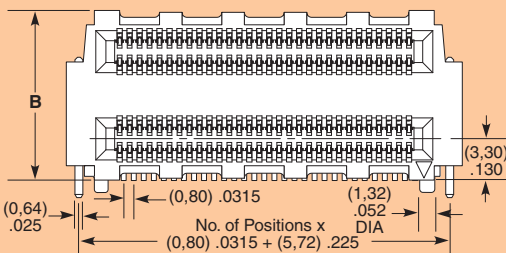
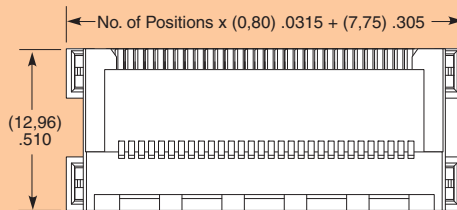
Accepts two individual cards for low profile stack or "Dual Stack" card set with industry standard 7mm board spacing

Solder charged terminations for easy board processing

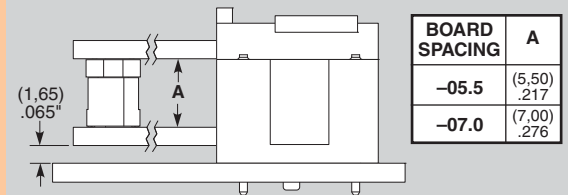
ALSO AVAILABLE

- Tin-Lead Solder Charge
 - Other card spacings
 - Single card elevated
 - Other plating options
- Call Samtec.

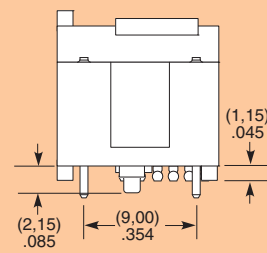
DSEC	NO. OF POSITIONS	LEAD STYLE	PLATING OPTION	BOARD SPACING	SOLDER TYPE	RA
	-30, -40, -50 (Per Row)	-01 = (1,60mm) .062" thick card	-L = 10µ" (0,25µm) Gold on contact, Matte Tin on tail	-05.5 = (5,5mm) .217" -07.0 = (7mm) .276"	-2 = Lead-Free Tin Alloy 96.5% Sn/ 3% Ag/ 5% Cu Solder Crimp	



TYPICAL APPLICATION



BOARD SPACING	A
-05.5	(5,50) .217
-07.0	(7,00) .276



BOARD SPACING	B
-05.5	(13,60) .535
-07.0	(15,10) .594

Note: Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM